

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An internal electrode paste, comprising electrode material powder, a binder resin containing a polyvinyl butyral resin and/or a polyvinyl acetal resin as the main component, ~~and a solvent, a plasticizer, and a ceramic powder,~~

wherein:

said electrode material powder comprises from 40 to 50 parts by weight of the entire internal electrode paste;

a polymerization degree of said polyvinyl butyral resin and/or polyvinyl acetal resin is from 1400 to 3600;

said binder resin comprises from 2.5 to 5.5 parts by weight with respect to 100 parts by weight of said electrode material powder and ceramic powder; and

said plasticizer comprises between 25 to 150 parts by weight with respect to 100 parts by weight of said binder resin.

2-7. (Canceled)

8. (Previously Presented) The internal electrode paste as set forth in claim 1, wherein an acetalization degree of said polyvinyl acetal resin is 74 mol% or less.

9. (Previously Presented) A production method of an electronic device, comprising the steps of:

preparing the internal electrode paste as set forth in claim 1;

forming a green sheet;

forming an internal electrode layer by using said internal electrode layer paste;

stacking said green sheets via internal electrode layers to obtain a green chip;

and

firing said green chip.

10. (Currently Amended) A production method of an electronic device, comprising the steps of:

forming an electrode layer on a surface of a first supporting sheet by using the internal electrode paste as set forth in ~~claim 1~~; claim 1;

pressing said electrode layer against a surface of a green sheet and adhering said electrode layer to the surface of said green sheet;

stacking the green sheet adhered with said electrode layer to form a green chip; and

firing said green chip.

11. (New) A production method of an electronic device, comprising the steps of:

preparing the internal electrode paste as set forth in claim 8;

forming a green sheet;

forming an internal electrode layer by using said internal electrode layer paste;

stacking said green sheets via internal electrode layers to obtain a green chip;

and

firing said green chip.

12. (New) A production method of an electronic device, comprising the steps of:

forming an electrode layer on a surface of a first supporting sheet by using the internal electrode paste as set forth in claim 8;

pressing said electrode layer against a surface of a green sheet and adhering said electrode layer to the surface of said green sheet;

stacking the green sheet adhered with said electrode layer to form a green chip; and

firing said green chip.